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PRODUCT SPECIFICATION

1.0 SCOPE

This Product Specification covers the 1.27 mm centerline (pitch) printed circuit board (PCB) connector series.

2.0 PRODUCT DESCRIPTION

2.1 DESCRIPTION, SERIES NUMBER, AND LINKS

DESCRIPTION	SERIES NUMBER
1.27 mm Pitch SLIM-GRID [®] Unshrouded Headers	87933

2.2 DIMENSIONS, MATERIALS, PLATINGS

See sales drawings for details on dimensions, materials and platings.

2.3 ENVIRONMENTAL CONFORMANCE

To fine product compliance information:

- a. Go to molex.com
- b. Enter the part number in the search field.
- c. At the bottom of the page go to "Environmental" to see compliance status.

2.4 SAFETY AGENCY LISTINGS

UL File Number: File E29179, Vol 10 CSA File Number: 152514 (LR19980)



CSA approval meets following standards/test procedures:

a) CSA std. C22.2 No. 182.3-M1987

b) UL-1977

* "C" and "US" mark adjacent to CSA signifies that the product has been evaluated to the applicable CSA and ANSI/UL standards, for use in Canada and US respectively.

Series 78120, 87933, 200989, 201021, 201022, 201173, rated 4.3 A, 125 Vac

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molex PRODUCT SPECIFICATION

3.0 APPLICABLE DOCUMENTS AND SPECIFICATION

3.1 MOLEX DOCUMENTS

Molex Solderability Specification SMES-152 Molex Heat Resistance Specification AS-40000-5013 Molex Moisture Technical Advisory AS-45499-001 Molex Package Handling Specification 454990100-PK

3.2 INDUSTRY DOCUMENTS

EIA-364-1000 UL-60950-1 UL-1977 CSA STD. C22.2 NO. 182.3-M1987

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PRODUCT SPECIFICATION

4.0 ELECTRICAL PERFORMANCE RATINGS

4.1 VOLTAGE

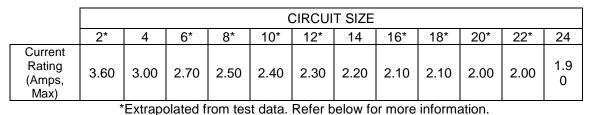
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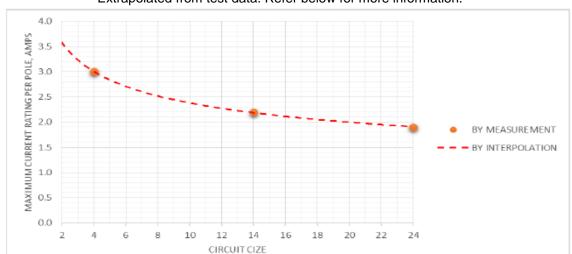
125 Vac

4.2 MAXIMUM CURRENT

4.3 Amps per Pole (only 1 contact powered up)

Current rating is application dependent and each application should be evaluated by the end user for compliance to specific safety agency requirements. The ratings listed in the chart below are per Molex test method based on a 30 °C maximum temperature rise over ambient temperature and are provided as a guideline. Appropriate de-rating is required based on circuit size, ambient temperature, copper trace size on the PCB, AWG WIRE, gross heating from adjacent modules / components and other factors that influence connector performance.





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PRODUCT SPECIFICATION

4.3 TEMPERATURE

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Operating Temperature Non-Operating Temperature : - 55 °C to + 105 °C : - 55 °C to + 105 °C

Field Temperature and Field Life: 65°C for 3 years (based EIA-364-1000, table 8)

Note: Temperature life test duration (section 6.3. item 2) is based on the assumption that the contact spends its entire life at the rated field maximum temperature (based on EIA-364-1000, table 8).

4.4 DURABILITY

Plating Type	Number of Cycles
Gold Plated	50

As tested in accordance with EIA-364-1000 test method (see Sec. 6.2 item 2 of this specification). Durability per EIA-364-09.

5.0 QUALIFICATION

Laboratory condition, sample selection and test sequences are in accordance with EIA-364-1000.

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6.0 PERFORMANCE

6.1 ELECTRICAL PERFORMANCE

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.1.1	Contact Resistance (LLCR)	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA (EIA-364-23) Note: Wire resistance and traces shall be removed from the measured value.	30 milliohms [Initial] [Maximum]
6.1.2	Insulation Resistance	Mate & unmount connectors; apply a voltage of 500 VDC between adjacent terminals and between terminals to ground. (EIA-364-21)	1000 Megohms [Minimum]
6.1.3	Dielectric Withstanding Voltage	Mate & unmount connectors; apply a voltage of 1000 VAC between adjacent terminals and between terminals to ground. Mate & unmount connectors; apply a voltage of 1250 VAC between adjacent terminals and between terminals to ground. (EIA-364-20)	No breakdown; Current Leakage < 5 mA
6.1.4	Temperature Rise	Mate connectors: measure the temperature rise of contact when the maximum DC rated current is passed. (EIA-364-70, Method 1)	Temperature Rise +30°C [Maximum]

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6.2 MECHANICAL PERFORMANCE

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.2.1	Connector Mate & Unmate Force	Mate and unmate connectors at a rate of 25.4 mm/min (EIA-364-13D, Method A)	Mate Force 15 N (24ckt) 10 N (4ckt) [Maximum] Unmate Force 3.0 N (24ckt) 0.5 N (4ckt) [Minimum]
6.2.2	Durability	Mate connectors up to 50 cycles at a maximum rate of 500 ±50 cycles/hr. (EIA-364-09)	Appearance: No Damage Contact Resistance: 15 milli0 [Maximum] [Change from Initial]
6.2.3	Reseating	Manually mate and unmate the connector with mating half for 3 cycles with rate of 5 cycles/min maximum. (EIA-364-09)	Appearance: No Damage Contact Resistance: 15 milliΩ [Maximum] [Change from Initial]
6.2.4	Terminal Retention Force (in Housing)	Axial pullout force on the terminal in the housing at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute. (EIA-364-29, Method C)	4.0 N [Minimum]
6.2.5	Vibration	Mate connectors and subject to the following vibration conditions, for a period of 2 hours in each 3 mutually perpendicular axis. Amplitude: 1.52mm (.060 inch) peak to peak Test pulse: half sine Sweep: 10->55->10 Hz in 1 minute Duration: 2 hours in each x-y-z axis. (EIA-364-28, Test Condition I)	Appearance: No Damage 15 milliohms [Maximum] (change from initial) Discontinuity: 1.0 μs [Maximum]
6.2.6	Mechanical shock	Mate connectors and subject to the following shock conditions, 3 shocks shall be applied along 3 mutually perpendicular axis. (total of 18 shocks) Peak value: 490 m/s sq. (50G) Test pulse : half sine Duration : 11 ms in each x-y-z axis (EIA-364-27B Condition A)	Appearance: No Damage Contact Resistance: 15 milliΩ [Maximum] [Change from Initial] Discontinuity: 1.0 μs [Maximum]

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6.3 **ENVIRONMENTAL PERFORMANCE**

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				TEOTO					
	ITEM DESCR						REG		
				Mate connec 5 cyc Temp °C	cles of:-	ose to ation			
					(Min	utes)	Anneara	nce: No Damage	
				-55 + 0/-5	3	30		ct Resistance:	
	6.3.1	Thermal S	hock	Transfer time from cold to hot		ximum	15 milliΩ [Maximum]		
				+105 + 3/-0		30	-	ge from Initial]	
				Transfer time from hot to cold		ximum			
				(EIA-364-3 Cond	2G Metho ition VII)	od A,			
	6.3.2	Temperatur	re Life	Mate Connec Temperatu Duration (EIA-364-17, Me	re: 105 ± 2 : 96 hours	2 °C 3.	Conta [N	nce: No Damage ct Resistance: 15 milliΩ /aximum] ge from Initial]	
	6.3.3	Cyclic Temp and Humi		Temperature Humidity Temperature Humidity Ramp times sh and dwell times Dwell times temperature an	te connector and expose to:- Temperature: $25 \pm 3 ^{\circ}$ C @ Humidity: $80\% \pm 3\%$ and Temperature: $65 \pm 3 ^{\circ}$ C @ Humidity: $50\% \pm 3\%$ mp times should be 0.5 hour dwell times should be 1.0 hour. Dwell times start when the nperature and humidity have ized within the specified levels.		Appearance: No Damage Contact Resistance: 15 milliΩ [Maximum] [Change from Initial] Dielectric Withstanding Voltage: No Breakdown Insulation Resistance: 1000 MegaΩ Minimum		
	6.3.4	Low Temperature Test		Mate connectors and expose to:			Appearance: No Damage Contact Resistance: 15 milliΩ [Maximum] [Change from Initial]		
	6.3.5	SO₂ Ga (Gold Plated			sity: 50 ± 5	5 ppm °C S	Appearance: No Damage Contact Resistance: 15 milliΩ [Maximum] [Change from Initial]		
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6.3 **ENVIRONMENTAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT		
6.3.6	Solderability	Unmate connector. Steam age for 8 hour ± 15 min. (precondition: Condition C) <u>SMT</u> Surface mount process simulation test Solder paste is deposited onto screen (e.g. ceramic plate) via stencil. The connectors are placed onto the solder paste print. Subject the substrate and component to the reflow process through a convection oven. Refer to section 8.0 for temperature profile. Flux type: ROL0	95% of the immersed area must show no voids, pin holes		
6.3.7	, Resistance to solder Heats SMT Convection reflow Sample to be passed through reflow over according to temperature profiles (shown in section 8.0) (EIA-364-56C, Procedure 6)		Appearance: no damage		

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7.0 TEST SEQUENCE GROUPS

Sequential Tests Group \rightarrow	1	2	3	4	5	6	7	8	9	10	1
Test or Examination $oldsymbol{\Psi}$											
Sample size	5	5	5	5	5	5	5	5	5	5	5
Resistance to Soldering Conditions	1	1	1	1	1	1	1	1			
Low Level Contact Resistance (LLCR)	2, 5, 7	2, 5, 7, 9	2, 5, 7, 9		2, 4	2, 4	2, 4	3, 7			
Insulation Resistance				2, 6							
Dielectric Withstanding Voltage				3, 7							
Connector Mate								2, 6			
Connector Unmate								4, 8			
Durability	3(a)	3(a)	3(a)					5			
Reseating	6	8									
Vibration			6								
Mechanical Shock			8								
Thermal Shock		4		4							
Temperature Life	4		4(a)								
Cyclic Temperature & Humidity		6		5							
Low Temperature Test					3						
SO ₂ gas (Gold plated)						3					
Salt Spray							3				
Pin Retention (in housing)									1		
Solderability										1	
Temperature Rise											1

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8.0 SOLDER INFORMATION

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Per SMES-152 and AS-40000-5013

*These specifications establish standard solderability test methods used to evaluate a products ability to accept molten solder. Solder Process Temperatures and Reflow Solder Profiles will vary based on application, equipment, solder paste, PCB thickness, etc.

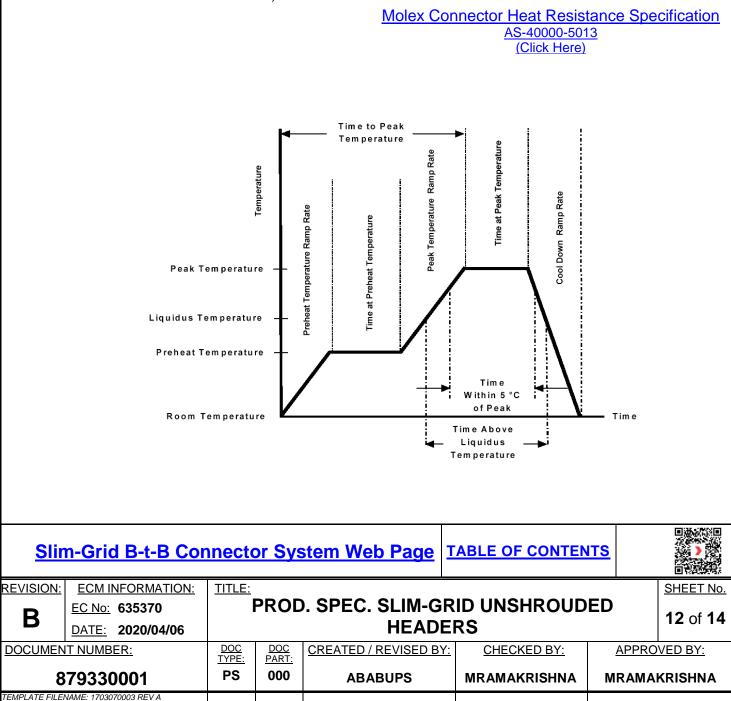
8.1 SOLDER PROCESS TEMPERATURE

Wave Solder: 245 °C Reflow Solder: 260 °C

Molex Solderability Specification SMES-152 (Click Here)

8.2 REFLOW SOLDERING PROFILE

(This profile is per AS-40000-5013 and is provided as a guideline only. Please see notes for additional information)



PRODUCT SPECIFICATION

Requirement
3 °C/sec Max
150 °C Min to 200 °C Max
60 to 180 sec
3 °C/sec Max
60 to 150 sec
260 +0/-5 °C
20 to 40 sec
6 °C/sec Max
8 min Max

9.0 PACKAGING

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Parts shall be packaging to protect the parts from damage during standard shipping, storage, and handling. Parts are packaged in bulk, tape and reel or tube. Refer to Packaging Specification, PK-87933-565 and PK-87933-300.

10.0 OTHERS

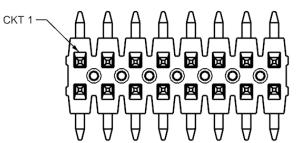
Although some discoloration could be seen on the solder tail after reflow, it does not impact on the product's performance.

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11.0 POLARIZATION AND KEYING OPTIONS

11.1 UNSHROUDED HEADER (Series: 87933)





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